12TH MICRO/NANO-ELECTRONICS PACKAGING AND ASSEMBLY, DESIGN AND MANUFACTURING FORUM

MiNaPAD Forum 2026

June 3rd – 4th
Minatec
Grenoble – France

- Exhibitions
- Conferences

OFFICIAL CATALOGUE

Organized by IMAPS France – International Microelectronics Assembly and Packaging Society
17 rue de l'Amiral Hamelin – 75016 Paris – France
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26th Nov. 2026

From Nano to Macro

Power Electronics and Packaging European Workshop

GREMAN – Polytech Tours
Amphithéâtre du Département électronique et énergie
7 avenue Marcel Dassault
37000 Tours - France

Organized by IMAPS France – International Microelectronics Assembly and Packaging Society
17 rue de l'Amiral Hamelin – 75016 Paris – France
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Summary

Location

Maison Minatec
3 parvis Louis Néel
38000 Grenoble centredecongres-maisonminatec@cea.fr

General Information

The registration Desk of MiNaPAD 2026 is located in the Minatec.

▸ **Adress**
Maison Minatec
3 parvis Louis Néel
38054 Grenoble – France

▸ **Opening Hours**

Wednesday June 3	8h30 – 18h30
Thursday June 4	8h30 – 16h00

▸ **Badges**
Participants are obliged to wear the official conference badge on all occasions.

▸ **Language**
The official language of MiNaPAD 2026 is English.

▸ **Coffee and lunch**
Coffee and lunch will be served in the exhibitor area only during the breaks between sessions. Lunch will be served in the exhibition hall.

▸ **Disabled persons**
Participants with disabilities are kindly requested to contact the congress organizers for assistance when entering the Minatec.

▸ **Non-smoking Policy**
MiNaPAD Forum 2026 will be a non-smoking conference. Smoking is prohibited in all meeting rooms and exhibition of the Minatec.

▸ **Liability**
In participant in MiNaPAD 2026, both participants and exhibitors agree that neither the MiNaPAD 2026 committee nor the Organizing secretariat assume any liability whatever. Participants and sponsors should organize their own health, travel and personal insurance.

Registration Fees

Non IMAPS member attendee	500 €
Conference ticket for iMAPS/ IEEE member	400 €
Conference ticket for students * and iMAPS member retired	0 €
Conference ticket for additional exhibitors	200 €
Speaker **	200 €
Chair and Sponsor	200 €

The prices are net amounts. Companies outside France are not subject to VAT. French companies have to pay 20 % VAT.

Fees cover access to all sessions, the exhibition, the welcome reception, the conference dinner (except for students) and the conference proceedings.

* The student fee is available for Bachelor and Master students.

** For every accepted paper one person from the group of authors will have to register at the author rate.

Welcome to MiNaPAD 2026!
Conference in Grenoble, France

Dear Conference Attendees, Speakers, Exhibitors, and Visitors,

It is a great pleasure to welcome you to the 12th Micro/Nano-Electronics Packaging and Assembly, Design and Manufacturing Forum (MiNaPAD). Since its inception in 2011, MiNaPAD has been rooted in a tradition of prestigious events and has become one of the most renowned European forums in the field of microelectronics packaging and integration. This year, the conference will be held from **June 3rd to 4th, 2026, at the Maison MINATEC Congress Center** in Grenoble, France –an iconic venue that hosted this event several years ago, still at the heart of one of Europe's most dynamic microelectronics ecosystems.

A return to a historic location to better move toward the future. Indeed, MiNaPAD is more than a conference: it is a unique platform for exchange and collaboration, where **academics, researchers, technology experts, and industry leaders meet** to explore the latest advances and create tomorrow's solutions.

This year's program showcases **36 exhibitors, representing major players across the packaging value chain** –from laboratories and inspection, assembly, and test services to materials and equipment suppliers. Participants will also benefit from **3 high-level keynote talks** delivered by influential industry leaders from STMicroelectronics, ESPAT-Consulting, and NexStage Ventures, offering strategic insights and forward-looking perspectives. Over the two days, **37 technical papers will be presented**, addressing key trends and challenges in packaging, including artificial intelligence, heterogeneous integration, and cutting-edge academic and industrial innovations. What an outstanding technical program!

Thanks to our generous sponsors, IMAPS France is pleased to enhance informal exchanges during coffee breaks and at the gala dinner, fostering meaningful discussions in a relaxed atmosphere. Encouraging the cross-fertilization of technical ideas between people from diverse backgrounds will also drive packaging technologies to a higher level –exactly what the electronics market expects. **After all, even the most brilliant die design can only become a successful product with the right packaging solutions. And those solutions are in your minds and hands, dear MiNaPAD attendees!**

Enjoy every moment of the conference, connect, learn, share, and take the most of everything MiNaPAD 2026 has to offer!

General Chairwoman
Valérie Volant (STMicroelectronics)

Sponsors Information

ASE, Inc. is the leading global provider of semiconductor manufacturing services in assembly and test. In a world that runs on semiconductor technology to achieve lifestyle, efficiency and sustainability goals, packaging innovation is at the heart of what ASE does. Today, ASE is delivering on the promise of heterogeneous integration, through advanced packaging, system-in-package, and chiplet solutions to meet growth momentum across HPC, Automotive, AI, 5G, and more.

STMicroelectronics (ST) is a global semiconductor leader, delivering innovative and sustainable solutions that are at the forefront of enabling smarter and more connected technologies. With a rich history spanning over three decades, ST combines cutting-edge expertise with a commitment to sustainability, empowering industries and individuals to address the challenges of today and shape a better tomorrow.

ST operates at the heart of diverse technological advancements, offering a comprehensive portfolio of products and solutions that serve key markets such as automotive, industrial, personal electronics, communications equipment, and the Internet of Things (IoT). Our technologies are designed to drive progress in areas such as:

- Smart mobility, advanced electric vehicles, autonomous driving, and connected cars
- Power and energy management, enabling energy-efficient systems and renewable energy solutions
- IoT and connectivity, fostering the seamless integration of devices and ecosystems
- Artificial intelligence at the edge, bringing intelligence closer to where data is generated

With a global presence in 35 countries, 14 manufacturing sites, and 80 sales offices, ST is uniquely positioned to support its customers and partners worldwide. Our team of over 50,000 employees, including 10,000+ R&D engineers, is dedicated to driving innovation and delivering high-quality, reliable solutions that meet the evolving needs of our customers.

At the core of ST's mission is a strong commitment to sustainability. As part of our vision for a greener future, ST has pledged to achieve carbon neutrality by 2027, embedding environmental and social responsibility into every aspect of our operations.

Through collaboration, innovation, and a relentless focus on excellence, STMicroelectronics continues to be a trusted partner for industries and organizations worldwide, enabling technologies that make a positive impact on people's lives and the planet.

Sentech Instruments develops, manufactures, and globally sells innovative capital equipment centered on thin films in semiconductor technology, microsystems, photovoltaics, nanotechnology and materials research. Sentech is expert in structuring and deposition of thin films by means of plasma process technology. Sentech offers systems for plasma etching, plasma enhanced chemical vapour deposition, and atomic layer deposition. Sentech provides innovative solutions for non-contact, non-invasive optical characterization using ellipsometry and reflectometry.
Founded in 1990, Sentech is a reliable partner to industry and scientific institutions with leading edge equipment, global sales and service network.

The Sentech motto "Erfolg durch Leistung" is a continuing commitment of all employees to achieve success by high standard of efficiency and customer service.

▸ **Plasma process technology**
Inductively Coupled Plasma (ICP) etch of silicon, quartz, and dielectrics Plasma Etch using:
- Capacitively Coupled Plasma (CCP) sources
- Deep Reactive Ion Etching (DRIE) Inductively
- Coupled Plasma Enhanced Chemical Vapour Deposition (ICPECVD)
- Thermal and Plasma Enhanced Atomic Layer Deposition (PEALD)

▸ **Thin Film Metrology**
- Spectroscopic ellipsometry
- Laser ellipsometry
- Reflectometry

NexStage Ventures is a Singapore-based technology and venture creation partner with global reach, helping startups, SMEs, and IDMs scale through advanced packaging and DFX in applications such as Power, Sensors & Photonics in AI and Edge AI platforms.
From Singapore, we provide direct access to Southeast Asia (SEA) and APAC ecosystems, with expertise in backend semiconductor manufacturing (OSATs, IDMs), panel-level packaging, wide-bandgap technologies (SiC/GaN), and sensor platforms.
We work hands-on with innovators to execute go-to-market, licensing, and venture-client models that connect advanced IP with manufacturing scale and market demand, enabling global commercialization and long-term value creation.

Krayden is a fabless manufacturer and distributor of specialty chemicals, adhesives & plastics with a focus on materials used in the semiconductor, electronics, automotive, energy and industrial markets. We research, develop, manufacture, handle and ship custom and innovative products. Our services are based on 4 pillars:

- Technical representation
- Technical Marketing
- Order fulfilment
- REACH Only representative

Hybrid SA is an independent t12SME based in Neuchâtel, Switzerland, specialized in advanced microelectronic assembly since 1989. We position ourselves on the industrialization segment that runs from TRL 4 to series production, designing assembly processes that are industrially compatible from the very first prototype rather than retrofitted later.
Our process portfolio covers wire bonding down to 15 µm pitch, flip chip in both solder and thermocompression variants, die bonding, stud and coin bumping, ultra fine pitch BGA, and SMD placement down to 01005. We work on 2.5D interposer integration and low-to-mid 3D stacking for heterogeneous assemblies combining logic, sensors and dedicated dies.
The markets we serve share the same constraints: traceability, process rigor and long-term reliability. They include space, medical, security, sensors, precision instrumentation and Swiss watchmaking. Our certification baseline covers ISO 9001, ISO 13485, IPC-A-610 together with J-STD-001 Space for manual soldering.
As an independent company, we offer short decision chains, a tight confidentiality perimeter, and the flexibility to handle complex low-volume projects.

Electron Mec is committed to providing world best in class tools, processes and services to High-Tech players in Europe, meeting and exceeding the requirements of its customers. Based in France, Italy, Germany, Switzerland and Spain we support our partners locally relying on process knowledge and experience.

Teledyne e2v is developing high end semiconductor components like very high-speed data converters, edge microprocessors, and image sensors used in many markets like healthcare, life sciences, space, transportation, security and industrial markets.

Today our customers can benefit from our assembly and test capabilities, developed for very demanding markets, and based on more than 40 years ‘experience and expertise in producing unique quality custom solutions to fit best with its customer’s needs.

Steering Committee

Valérie Volant (STMicroelectronics)
Jean-Luc Diot (Assemblinnov)
Romain Coffy (STMicroelectronics)
Jean-Charles Souriau (CEA-LETI)
Jean-François Sauty (ASE Europe)
Laurent Mendizabal (CEA-LETI)
Alexandre Val (Valeo)
Jerome Lopez (ST Microelectronics)

Main topics

▸ **Sustainability:** Sustainable packaging cases with Ultra-Precise Dispensing avoiding material waste compared to other technologies and environmental impact study of 3D integration modules.
▸ **Reliability:** Several reliability behavior studies under thermal, electrical, or larger stresses applied on different types of packages, WLCSP, power PCB or Bipolar Junctions test vehicles.
▸ **Characterization:** Various characterization methods are presented and used for different purposes: warpage control, bonding or adhesion failure, and micro-mechanical test on innovative metal stacks.
▸ **Process Optimization:** Several optimizations are presented in this section, notably at surface treatment level for interconnections process or power devices assembly.
▸ **Dispensing technologies:** Monitoring optimizations to increase performance of dispensing technologies, for 2 component adhesives deposition and Jet Dispensing.
▸ **Attachment Materials:** New materials development results for B-Stageable adhesives applied on Mems and advanced Solder-TIM for Asics.
▸ **Sintering materials:** Results sharing around various sintering conditions, and for different applications as power devices
▸ **Interconnections:** Several interconnect innovations, from wire bond to low scale bumping, and exploring additive technologies.
▸ **Flip Chip Process:** New achievements for flip chip technologies, at material level to enhance storage and placement accuracy to serve heterogeneous integration and optoelectronic assemblies.
▸ **Fan-out:** Innovative design for RF application using fanout technology and Fan-out industrialization in europe
▸ **Advanced packaging:** New materials demonstration in advance packaging, from aluminum in TGV to new dielectrics for hybrid bonding.
▸ **3D advanced:** Innovative use of 3D micromachining to serve advanced packaging solutions.
▸ **PCB Substrates:** Innovation around laminated package substrates, from glass core and to high density vias.
▸ **Packaging architecture and Heterogeneous Integration:** Combination of packaging innovations and architectures to meet futures market expectations.

Keynotes

Keynote 1 **Wednesday June 3rd**

IDM End-to-End Co-Optimization of Front-End and Back-End for Robust, Cost-Effective Microelectronics Products

Corinne Crégut

R&D director, STMicroelectronics, France

I began my career with a PhD in physics in 1998, which laid the foundation for my expertise in semiconductor modeling and simulation. In 2003, I took the lead of a team developing software solutions to predict parasitic effects and improve circuit performance before manufacturing. Later I expanded my scope into project management, leading multidisciplinary projects in optical sensors and connected devices. After earning PMI certification and managing project teams, I moved into packaging R&D in 2022. Today, I'm R&D Packaging Director at ST Grenoble, leading 120 people and driving laminate and optical packaging innovation from prototype to production.

Emmanuelle Serret

R&D director, STMicroelectronics, France

I joined ST 24 years ago after earning a PhD in condensed matter physics.I began my career in BiCMOS technologies R&D in 2002. In 2007, I moved into design enablement, leading DTCO initiatives and managing the team responsible for Design Rule Manuals across multiple technologies.
In 2020, I was appointed R&D Director, overseeing mask enablement and physical characterization labs. Since 2024, I have been leading the Technology Enablement & Reliability department, managing ~300 people focused on developing design and mask solutions for manufacturable and reliable products.

▷ Keynote Summary

This keynote addresses the co-optimization of front-end (FE) and back-end (BE) development flows in microelectronics in order to secure cost, time-to-market and quality targets for advanced products. In the current context of increasingly complex paths from silicon design to fully tested devices, we first clarify the respective scopes and interfaces of FE activities (process performance, process control monitoring, scribe line design and Design Enablement and BE activities (electrical wafer sort, sawing, assembly into package, test and finishing).
We highlight the central challenge: BE operations must be performed within the constraints defined by FE technology and layout, while FE must remain robust to BE processes and package-level stresses.
We then present a structured co-optimization approach. On the FE side, technology design rules are extended to explicitly embed BE constraints on seal rings, pad structures, BEOL, ensuring Package-robust silicon layouts. Scribe line architectures are optimized in terms of width and content to balance die area utilization, monitoring needs and sawing technology capabilities.
On the BE side, package architectures (e.g. WLCSP, BGA...) and assembly design rules are selected in coherence with FE dimensions and technology options, while sawing processes are chosen and tuned according to wafer configuration and package type.
Chip-package interaction (CPI) risks are mitigated through multi-physics

modeling (thermo-mechanical behavior, interface delamination, piezoelectric effects) combined with dedicated qualification plans.
The outcome of this work is a set of guidelines ensuring pad ring optimization, linking sawing techniques, optimized scribe streets according to FE technology. We show how this integrated methodology improves cost effectiveness through optimized gross die per wafer, assembly flow and package architectures, shortens time-to-market via predictive modeling and early CPI risk mitigation, and enhances quality through focused CPI qualification strategies.
Finally, we discuss the specific value proposition of an Integrated Device Manufacturer (IDM), compared with a Foundry/OSAT model, in orchestrating this end-to-end co-optimization. We also outline future extensions towards emerging integration schemes such as 3D wafer-to-wafer, high-integration die-to-wafer, panel-level packaging and wide bandgap technologies such as SiC.

Keynote 2 **Wednesday June 3rd**

Electronics Packaging in Europe Where we are three years after EU Chips Act 1.0 ?

Steffen Kröhnert
President & Founder, ESPAT-Consulting, Germany

Since 2019 Advisor & Lead Consultant Europe - Advanced Packaging Technology @Global Electronics Association/IPC Subject Matter Expert - Advanced Packaging @SEMI Europe.
Until June 2019, worked for 22 years in different Semiconductor Packaging R&D, Engineering, and Management positions at large IDMs and OSATs in Germany and Portugal (Siemens, Infineon, Qimonda, NANIUM, and Amkor).
In 2016 founded and since chaired or co-chaired the European SEMI-integrated Packaging, Assembly, and Test - Technology Community (ESiPAT-TC), a special interest group in SEMI focusing on manufacturing in Europe.
Authored or co-authored 23 patent filings and many technical papers in the field of Packaging Technology.
Co-edited two textbooks about "Embedded and Fan-Out Wafer and Panel Level Packaging Technologies".
Active member of many technical and conference committees of IEEE EPS, SEMI, IMAPS, and EPoSS.
IEEE EPS Program Director Region 8 (EMEA) and member of the Board of Governors.
Holds an M.Sc. in Electrical Engineering and Microsystems Technologies from the Technical University of Chemnitz, Germany.

▷ Keynote Summary

The EU Chips Act (officially EU Regulation 2023/1781) officially entered into force on September 21, 2023. The aim of the law is to strengthen Europe's competitiveness and resilience in the field of semiconductor technologies and to increase its share of global chip production to 20% by 2030.
Europe, like many other regions worldwide, is witnessing unprecedented investment and collaboration in semiconductor technologies capabilities development and manufacturing capacities increase. This is certainly true and publicly visible for wafer manufacturing in the frontends (FE), but also the backends (BE) for assembly, interconnection, packaging and test is evolving in the ecosystem.
We are at an inflection point in semicon-

ductor industry. Advanced Packaging (AP) has become the primary driver for continuing Moore's Law as traditional monolithic scaling hits physical limits. In terms of its economic benefit - specifically, the reduction in cost per transistor - largely stopped holding true around the 28nm technology node. By using chiplets and heterogeneous integration, engineers combine multiple, specialized, smaller dies into a single package (System-in-Package and Heterogenous System Integration), improving performance, lowering costs, and reducing power consumption.

The semiconductor industry is currently experiencing a strong growth phase in both, FE and BE, the latter namely through leading-edge AP. That market is entering a new phase of strategic importance, projected to grow from $44.82 billion in 2026 to $70.41 billion by 2034 (Source: Fortune Business Insights). As traditional semiconductor technology node scaling reached its limits, AP technologies such as 2.5D/ 3D ICs, Fan-Out Wafer/ Panel Level Packaging, and chiplet-based architectures are now the enabler of higher performance, improved power efficiency, and larger system integration. The massive growth is driven by Artificial Intelligence (AI) and High-Performance Computing (HPC) applications, with significant expansion projected through 2026 and beyond. But the main players are not European, so what's in for Europe?

The presentation is exploring the dynamic landscape of Semiconductor Packaging, Assembly, and Test in Europe as a sector that is pivotal for the region's digital sovereignty and industrial competitiveness. What was done in the last three years? What's next?

Keynote 3 **Thursday June 4th**

Connecting the Dots: From Technical Excellence to Ecosystem Leadership

Jérôme Teysseyre

Co-Founder, NexStage.Ventures, Singapore

Jerome Teysseyre is a senior semiconductor industry leader with extensive experience shaping global technology, packaging, and business strategies in large international companies.

He has held senior leadership roles at STMicroelectronics, Fairchild Semiconductor, and onsemi, operating across Europe, Asia, and the Americas.

His career has centred on driving innovation and differentiating technology through strategy, and building ecosystems that connect design, manufacturing, and markets, contributing to around 50 U.S. patents.

Jerome is the co-founder of NexStage.Ventures, where he advises companies on technology differentiation, go-to-market strategy, and ecosystem building to enable next-stage growth.

For decades, our industry competed on technical superiority: faster, smaller, more efficient. Innovation was driven by pushing the limits of physics, materials, and process integration. Today, however, even the most advanced technology cannot succeed in isolation.

The real frontier of innovation is no longer inside the chip or the package. It lies between organizations, across ecosystems, and at the intersection of disciplines. This perspective is shaped by years spent in senior and executive management roles within large global companies, leading packaging and integration teams worldwide across signal ICs, sensors, power devices, and advanced packaging platforms.

Across these experiences, one conclusion became unavoidable: while technical excellence remains essential, it is no longer sufficient. The next leaders of our industry will not simply design better technologies. They will design better ecosystems.

In this new era, innovation does not accelerate through tighter control or local optimization. It accelerates through connection, between design and manufacturing, between companies, and between strategic vision and execution.

▷ Keynote Summary

Technology alone no longer defines competitive advantage. AI, electrification, mobility, and energy transition are not product challenges; they are ecosystem transformations that demand coordination across disciplines, industries, and geographies.

Advanced integration and packaging are increasingly strategic, acting as bridges between system architecture, silicon, manufacturing, and application. Experience from global markets shows that packaging choices now directly impact performance, cost, scalability, resilience, and time-to-market.

Drawing on high-level management responsibilities held in recent years, this keynote is grounded in real-world situations where strategies had to be defined and implemented at scale. In these environments, the primary constraint was rarely physics alone it was coordination: aligning roadmaps, incentives, organizations, and partners.

Companies and organization that remain siloed may continue to innovate locally, but they compete globally at a disadvantage. Value creation is shifting from isolated component performance to orchestrated systems.

Leadership today means connecting technologies, aligning ecosystems, and building trust across boundaries. The future belongs to those who can connect the right dots : early, decisively, and collectively.

Extra session **Wednesday June 3rd**

PEPR Packaging (INPACK) and ReNaPack - Projects overview

O.Ducloux (CEA), D. Henry (CEA Leti), H. Granier(CNRS Laas) – France

Short presentations of French scope programmes, presented in French only

On April 1, 2026, the INPACK packaging PEPR (Project for the Development of Packaging Resources) was launched. This project aims to enable the development of innovative packaging building blocks through four upstream projects, as well as to establish a distributed packaging academic platform called Renapack. All the actions planned within this new PEPR will be presented during this presentation. This presentation will be given in French language and is intended for a French audience.

Conference Rooms

WEDNESDAY June 3rd

TIME	WHAT	WHERE
8h30	Registration/welcome	Exhibition Hall
9h	Opening	Auditorium
9h10	Keynote	Auditorium
10h	Sessions A	Auditorium
	Session B	Chrome
11h	Exhibition/Coffee break	Exhibition Hall
11h30	Session C	Auditorium
	Session D	Chrome
12h30	Lunch	Exhibition Hall
13h40	Session E	Auditorium
	Session F	Chrome
15h45	Exhibition/Coffee break	Exhibition Hall
16h15	Session G	Auditorium
	Session H	Chrome
17h45	Exhibition Hall	Exhibition Hall
17h50	Extra session	Auditorium
18h30	Social Event Departure	Domaine de Charmeil

THURSDAY June 4th

TIME	WHAT	WHERE
8h	Opening MiNaPAD	Exhibition Hall
8h40	Keynote	Auditorium
9H15	Session J	Auditorium
	Session K	Chrome
10h15	Exhibition/Coffee break	Exhibition Hall
10h45	Session L	Auditorium
	Session M	Chrome
12h15	Lunch	Exhibition Hall
13h15	Session N	Auditorium
	Session O	Chrome
14h15	Exhibition/Coffee break	Exhibition Hall
14h30	Session P	Auditorium
16h	Closing	Auditorium

Conference Overview

Wednesday June 3rd

8h00	**Registration & Welcome to MiNaPAD – Coffee & Soft drink sponsored by ASE** Exhibition Hall	
9h00	**Opening** Auditorium Valérie Volant	
9h10	**Keynote 1 ▶ IDM End-to-End Co-Optimization of Front-End and Back-End for Robust, Cost-Effective Microelectronics Products** Auditorium Corinne Crégut & Emmanuelle Serret, R&D directors, STMicroelectronics, France	
	Session A ▶ Dispensing technologies Auditorium	**Session B ▶ Attachment materials** Chrome
10h00	**Real-Time Inline Monitoring of Adhesive Mixing for Process Control in Electronics Packaging** R. Shankar, Krayden, Philippines	**Development of an electrically conductive, B-stageable adhesive for reliable ceramic MEMS package assembly** J. Schuermans, Roartis, Belgium
10h30	**Advances in Sintering Materials for Varying Substrate Sizes "From Slit-Nozzle Dispensing for large substrate area to Jet Dispensing for small diodes"** A.M. Laügt, Inventec, France	**AI Data Centre ASIC Cooling – Advanced Solder-TIMs** K. Vijay, Indium Corporation, United Kingdom
11h00	**Exhibition Opening – Coffee break sponsored by STMicroelectronics** Exhibition Hall	
	Session C ▶ Sustainability Auditorium	**Session D ▶ Sintering materials** Chrome
11h30	**Additive manufacturing fabrication and LCA of PCBs for remote control** T. Jamal, CEA Liten, France E. Whitmore, 4MOD Technology, France	**Pressure-less silver sintering for power application: impact of silver, gold or copper surface finishes on microstructure and mechanical performances** M. Veluire, UGA / CEA Leti, France
12h00	**Learn about 3D integration through its environmental impact** M. Billaud, CEA Leti, France	**Evaluation of various Cu-sinter materials using different sintering atmospheres and conditions** S. Merkert, PINK GmbH Thermosysteme, Germany
12h30	**Exhibition – Lunch sponsored by Teledyne e2V** Exhibition Hall	
13h40	**Keynote 2 ▶ Electronics Packaging in Europe - Where we are three years after EU Chips Act 1.0 ?** Auditorium Steffen Kröhnert, President & Founder, ESPAT-Consulting, Germany	

	Session E ► Packaging Architecture Auditorium	**Session F ► Reliability** Chrome
14h15	**Low Profile Waterproof Pressure Sensor** A. Ratti, STMicroelectronics, Italy	**Platform for the characterization of electronic components during aging under thermal and electrical stresses** C. Rouleau, Université de Bordeaux / EDF, France
14h45	**Case studies: applied reliability for European electronics** M. Wallrodt, Micro Systems Engineering GmbH, Germany	**Thermal Cycling Durability Model for Lead-Free Wafer Level Packages** J-B Libot, Hooke Electronics, France
15h15	**Toward a reproducible fabrication process of a magneto-optic trap for ultra-cold atom sources.** L. Boudier, Université de Toulouse/ LAAS-CNRS, France	**Sinter Lamination in Planar Transformer PCB Technology: Reliability Assessment and Path Towards ECSS Standardization for Aerospace Applications** I. Platteaux, Advanced Circuit Boards (ACB), Belgium
15h45	**Exhibition – Coffee break sponsored by Krayden** Exhibition Hall	

	Session G ► Process optimization Auditorium	**Session H ► Characterization** Chrome
16h15	**Optimizing indium bump deoxidation through 3D surface profilometry** G. Chaumy, SET Corporation, France	**Warpage control during assembly process and panel-level RDL formation for heterogeneous integration** Y. Maruyama, Resonac Corporation, Japan
16h45	**Atmospheric Plasma Processes for Sustainable Oxide Reduction and Adhesion Enhancement in Power Electronics Packaging** D. Ben Salem, Plasmatreat GmbH, Steinhagen, Germany	**Synchrotron X-ray microtomography, an advanced imaging technique to reveal electronic devices packaging and assembly** E. Boller, The European Synchrotron, France
17h45	**Enhancement of Gold-to-Gold (Au-Au) Bonding by atmospheric plasma surface treatment** D. Pascual, ONTOS Equipment Systems, USA	**Multi-scale micromechanical testing for new Polymer Core Solder Ball interconnection's reliability in operating conditions** Y. Marthouret and X. Carridroit, EMSE/SMS/Physique et mécanique des matériaux (PMM), France
17h45	**Exhibition** Exhibition Hall	
17h50	**Extra session ► PEPR Packaging (INPACK) and ReNaPack – Projects overview** **Auditorium** O.Ducloux (CEA), D. Henry (CEA Leti), H. Granier(CNRS Laas) – France *Short presentations of French scope programmes, presented in French only.*	
18h30	**Social Event: Departure**	

Conference overview

Thursday June 4th

8h00	**Opening exhibition and conferences** – Coffee & Soft drink sponsored by Sentech and Teledyne e2V Exhibition Hall
8h30	**Welcome** Auditorium
8h40	**Keynote 3 ► Connecting the Dots: From Technical Excellence to Ecosystem Leadership** Auditorium Jérôme Teysseyre, Co-Founder, NexStage.Ventures, Singapore

	Session J ► 3D advanced Auditorium	**Session K ► Advanced packaging** Chrome
9h15	**Glass 3D structuring via FLICE technology for advanced packaging applications** A. Lecomte, Université de Toulouse/ LAAS-CNRS, France	**Aluminum Filled Through Glass Vias (TGV): From Idea to Applications** N. Burmeister, Fraunhofer Institute for Silicon Technology, Germany
9h45	**Build-Up Fan-Out Wafer-Level Packaging with In-Package Fabrication of 3D Integrated Passive Devices Enabled by 3D- RDL and TPVs for RF/mmWave Applications** A. Ghannam, 3DiS Technologies, France	**New dielectric materials for low temperature hybrid bonding** J. Maurice, UGA/CEA Leti, France
10h15	Exhibition – Coffee break sponsored by Hybrid SA Exhibition Hall	

	Session L ► PCB substrates Auditorium	**Session M ► Interconnections** Chrome
10h45	**Substrate Reliability in Practice: Testing Methods and Design Recommendations for IC Packaging** D. Capeder, Dyconex AG, Switzerland	**Innovative Pressure less Wire Bonding for High-Power Systems** M. Fettke, PacTech - Packaging Technologies GmbH,Germany
11h15	**Pioneering Bottom-Up Copper Plating: Advanced Pillar-Like Metallization for High Aspect Ratio Through Glass Vias** S. Dharmarathna, MacDermid Alpha Electronics Solutions, USA	**Ultra-Precise Dispensing for Advanced Microelectronics Packaging: Materials Versatility and Long-Term Process Stability** F. Granek, XTPL SA, Poland
11h45	**Application of Glass Core Substrates for Chiplet Systems** C. Landstorfer, Fraunhofer IZM, Germany	**Investigation of wafer level downscaling challenges in electroplated lead-free micro bumps for ultra-fine pitch interconnects** S. Grolier-Lee, CEA Leti, France
12h15	Exhibition – Lunch sponsored by Sentech Exhibition Hall	

	Session N ► Fan-Out Auditorium	Session O ► Flip-Chip Chrome
13h15	**Fan Out Wafer Level Packaging – European Manufacturing for Small to Mid-volumes** M. Dreissigacker, AEMtec GmbH, Germany	**Underfill adhesive: Thermomechanical and Thermal Storage Optimization** O. N'Diaye, Protavic International, France
13h45	**Radar with Integrated Antennas based on Fan-Out Wafer-Level Packaging RDL-First Integration** A. Garnier, CEA Leti, France	**Sub-micron placement accuracy – the era for heterogeneous integration and optoelectronic assemblies** M. Fraubaum, BESI Austria GmbH, Austria
14h15	Short Break Exhibition Hall	

	Session P ► Heterogeneous Integration Auditorium
14h30	**Innovative assembly and test developments for next gen power and RF semiconductors** R. de Wit, CITC/TNO, Netherlands
15h00	**Packaging and assembly challenges in Photovoltaic (PV) modules: Focus on numerical simulation of the delamination behavior of PV assembly** B. Chambion, UGA/CEA Liten, France
15h30	**Innovative Power Package Solutions for AI GPU Accelerators: UTAC's Two-sided Cooling SPS, High Thermal EMC, and SiP Power Module Advancements** M. Choi, UTAC Group, USA
16h00	Closing MiNaPAD 2026 Conference Valérie Volant

Photo Studio

Please after each session speakers and chairman to go room near Chrome room for picture, Thank you.

Social Event

▸ **Domaine de Charmeil**
154 impasse de la grande grange
38210 Saint-Quentin-sur-Isère

Rocade, direction Lyon
Sortie n°12 – Valence par D 1532
Suivre panneaux Valence et Saint-Quentin avant Saint-Quentin-sur-Isère, le Golf Hôtel est indiqué, entrée à droite

18h30 Bus transportation
meeting point: Minatec
3 parvis Louis Néel
38000 Grenoble
19h00 Appetizers & Music
20h00 Dinner
22h30 Return to Novotel Centre Grenoble

▸ **Sponsors**

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Group ACB

Booth 34

Activities

Group ACB is a PCB manufacturer based in Europe with 3 manufacturing sites (2 in France, Atlantec & Cibel and one in Belgium ACB). We are focus on high technology and high reliability PCB.
We can support quick turn over manufacturing (QTA) in many technologies such as Rigid, HDI, Flex-Rigid, Sequential, Flex-Rigid HDI, Thermal management, RF and HF.
We are also specialist on PCB for the Semiconductor market; we can support all kind of applications with thin tracks and gaps made with organic PCB technology

Products

From ATE Loadboards (for wafer or final test) to evaluation boards for customer, ACB can also supply your HAST and HTOL reliability boards.
Main characteristics are 6,4 mm thick PCB , dimensions 600x700 mm , large drill aspect ratio, inhouse plating for reliable contacting, laser drill, last generation etching process for thin and controlled impedances lines, and induction press.
ACB is also qualified by ATE manufacturing companies for hyper and RF PCB.
Consistently new released substrates offer to customer to reach stretched test performances.
Time to market oriented organization with QTA (Quick Turn Offer) fab for very high demanded customers.

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Accelonix

Booth 13

Activities

Accelonix is a solutions provider of equipment, materials and software for electronic & micro-electronics assembly. Accelonix group focus is western Europe, for industrial and research institutions, working in all sectors of the electronics industry.
Our service is based on close partnership with all Accelonix suppliers, through exclusive agreements in combination with in-house technical team, permuting rapid and efficient customer services and technical support.
Our success is built on an attitude for « innovation & opportunity » in synergy with a mix of complementary products and technologies. It is our intention that our customers benefit directly from this synergy, in addition to our contact and experience base, built up from over 25 years existence of Accelonix, and many decades of industrial experience for those in the company.
In addition to activities in Micro-assembly, Accelonix France is also active in the domains SMD pcb assembly and test, and Hi-rel component supply.

Product

- dicing – wafer, glass, ceramic, composite
- dispensing & jetting – pumps and machine for glue, solder, glob top, underfill,
- die attach and die sorting: MCM, Hybrid, silver glass, flip chip, eutectic
- wire bonders: manual & Automatic; fine & heavy; wedge & ball
- Battery bonding (Wirebonding, Smartwelding, Laserwelding)
- back-end plasma process – batch, on-line for wirebond and surface treatment
- vacuum pressure furnace – low void, flux free solder & brazing & wafer bonding
- hermetic sealing – seam sealing
- clean room & dry cabinets – modular and integrated solutions
- modular bond test – pull, shear, flex, stud pull
- screen printing – for ceramic substrates

Equipment for Metrology

- Non-surface contact profilometry
- Themal warpage metrology

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AEMtec

Booth 11

Activities

AEMtec is one of the global acting specialists for the development and production of a variety of precision optoelectronic products. The wide technology portfolio and outstanding services in the area of miniaturization mean reliable solutions like components, modules and complete systems.
The motivation is not only to drive innovations but also to accompany the customer along the entire value chain.
Our customer-specific products are complex electronic assemblies with precise component placement requirements. In a cleanroom environment (ISO 5-8) AEMtec offers a unique spectrum of high-end chip level technologies. AEMtec is ISO 9001, ISO 13485 (Medical) and ISO 14001 (Environmental) certified.

Product description

Wafer Back-End Services (UBM, SBA, Dicing), Chip on Board and SMT Technologies, optical components, VCSEL Photodiodes, MEMS, Moded Optical Interfaces and System Integration Packaging.

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Activities

Amadyne founded in 2000 is located in Bühl in the Rhine valley near Baden Baden from where the company offers direct support to the German speaking countries. In other countries Amadyne is represented by selected dealers. Amadyne offers compact, flexible solutions for the automation of microelectronic assembly manufacturing. Our systems provide for the precise production of sophisticated and complex components for micro systems engineering, micro opto-electronics and micro mechanical assemblies suitable for:

- small-medium-large production batches
- standard and advanced packaging processes
- complex high mix & high quality products
- integration of customer specific solutions
- short setup times
- fast product changeover

Product

Amadyne's current product portfolio includes the CATII and fab platforms.

▸ **CATII platform:**
The CATII is an automatic Micro Assembly System for picking and placing of components from various presentation formats, as well as for applying adhesives. Currently there are two versions from the CATII available called CATII and CATIIL with different working areas. Bath systems use AMADYNE's advanced software platform with its fully developed process capabilities. The system is quick to program and simple to operate for the assembly of products within the microsystems industry.

▸ **fab platform:**
The fab is a compact, flexible automatic assembly platform for handling virtually any kind and size of component, as well as for applying adhesives. Typical applications are pick & place, dispensing, sorting, inspection and test functions. Currently there are two versions from the fab available called fab1 and fab2. Bath systems uses the latest hardware technology, combined with a network transparent fully graphical contrai software, interacting with an SQL server based backend.

Amadyne

Booth 25

AMADYNE. GMBH

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ASE, Inc.

Booth 35

Activities

ASE, Inc. is the leading global provider of semiconductor manufacturing services in assembly and test. In a world that runs on semiconductor technology to achieve lifestyle, efficiency and sustainability goals, packaging innovation is at the heart of what ASE does. Today, ASE is delivering on the promise of heterogeneous integration, through advanced packaging, system-in-package, and chiplet solutions to meet growth momentum across HPC, Automotive, AI, 5G, and more.

Portfolio

The Company develops and offers complete turnkey solutions covering IC packaging, design and production of interconnect materials, front-end engineering test, wafer probing and final test, as well as electronic manufacturing services through USI, Inc. To learn about our technology advances and our VIPack™ platform, designed to enable vertically integrated package solutions, please contact your regional ASE office, visit aseglobal.com or follow us on LinkedIn.

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Biesterfeld

Activities

Biesterfeld group is an international distribution and service company in the chemical industry founded in 1906 :

- Subsidiaries at more than 50 locations serving customers in over 120 countries
- Independent, family-owned company
- Leading distributor of plastics, rubber, base and specialty chemicals
- 4 core business divisions: Biesterfeld Plastic, Biesterfeld Spezialchemie, Biesterfeld Performance Rubber, Biesterfeld International
- Group Sales (2018): 1.39 bn €
- Employees (2018): 1100

Product

In the electro, electronics and energy sector we offer adhesives and sealants, casting compounds, elastomers, gels, coatings, and electrical and thermal conducting materials, based on silicone, epoxy, polyurethane and acrylate. You can find our large product range for the electronics, automotive and solar industries, as well as lighting and heat management.

Booth 18

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CCI Eurolam

Booth 29

Activities

CCI Eurolam is your EMEA partner for the supply of special materials and chemicals for the electronic industry. We are waiting for your visit on our booth to present our suppliers latest innovations for electronic design and manufacturring including: latest generation of Indium Corporation materials for soldering, fluxing, sintering and thermal dissipation from semi-conductor level to Pcba assembly.

Product

Microelectronics and semiconductor packaging:

- Qunity metallization for UBM, RDL, Cu pillars as well as polymers and dielectrics for RDL
- Photolithography resins and solutions for developing, cleaning and eteching
- Tatsuta bonding wires

Pcb materials & chemicals:

- Emc latest generation of Pcb substrate to meet microwave, low loss requirements as well as high performances, high Tg and IC substrate
- Qunity plating, developing, striping
- Dry film
- Process equipment

Electronic inks:

- Micromax functional inks and substrate for printed electronics (heating, stretchable, thermoforming, PI resistive,...). “Grenne Tape” LTCC and high temperature “thick film inks” inks
- Piezotech inks
- Agfa Pedot PSS based materials

Adhesive :

- Bostik adhesive solutions for the electronics

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CDS Electronique

Activities

CDS Electronique distributes materials for micro-electronic manufacturing (packaging) and offers equipment for microdispensing and ink-jet printing. Do not hesitate to contact us, we can carry out tests from our showroom in Bussy-Saint-Martin (77).

Product

- Encapsulation- underfill resins NAMICS
- Conductive adhesive - (high thermal conductivity) NAMICS
- Die-attach NAMICS
- Nano-inks (silver , gold) XTPL
- Micro-dispensing solution MUSASHI Engineering
- Nano- dispensing expertise XTPL
- Impression ink-jet MICROCRAFT

Booth 20

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CEA-Leti

Booth 1

Activities

CEA-Leti, a technology research institute at CEA, is a global leader in miniaturization technologies enabling smart, energy-efficient and secure solutions for industry. Founded in 1967, CEA-Leti pioneers micro-& nanotechnologies, tailoring differentiating applicative solutions for global companies, SMEs and startups. CEA-Leti tackles critical challenges in healthcare, energy and digital migration. From sensors to data processing and computing solutions, CEA-Leti's multidisciplinary teams deliver solid expertise, leveraging world-class pre-industrialization facilities. With a staff of more than 1,900, a portfolio of 3,100 patents, 11,000 sq. meters of cleanroom space and a clear IP policy, the institute is based in Grenoble, France, and has offices in Silicon Valley and Tokyo. CEA-Leti has launched 70 startups and is a member of the Carnot Institutes network.
Follow us on www.leti-cea.com and @CEA_Leti.

Product

CEA-Leti offers a wide range of packaging solutions and tailored developments for industrial partners:

- Fast data exchange technologies: High density 3D-IC, active interposers & advanced photonics
- Design technologies: Partitioning studies for best Power/Performance/Area/Cost trade-off & 3D CAD flow
- 3D integration and packaging technologies: TSV, routing, redistribution layers, connecting - µbumps, hybrid bonding
- Heterogeneous integration: Fan-out wafer lever packaging tailored for various applications and flex substrates for ultra-thin and conformable systems

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CEA-Leti

Cicor

Booth 16

Activities

Cicor is a leading pan-European partner for the design and manufacture of high-reliability electronic solutions. Headquartered in Switzerland and founded in 1966, Cicor delivers full-cycle services – from development to series production – enabling highly customised, mission- and life-critical applications.

Serving the healthcare technology, industrial and aerospace & defence markets, Cicor combines engineering expertise with high-precision manufacturing to bring innovative ideas to life.

With a global production network and ISO-certified facilities, Cicor offers a comprehensive portfolio ranging from printed circuit boards and microelectronics to complete electronic systems. Together with its customers, Cicor creates electronics that make the world a healthier, more connected and safer place.

Product

Cicor offers a comprehensive portfolio of electronic solutions, supporting customers from concept to volume production. Combining engineering expertise with advanced manufacturing, Cicor delivers highly reliable, customised products for demanding applications.

▸ **Printed Circuit Boards (PCBs):** Design support and manufacturing of standard, HDI and U-HDI, rigid, rigid-flex and flex PCBs for high-density and high-reliability applications.

▸ **Advanced Substrates:** Thin- and thick-film substrates for sensors, power modules and microelectronic packaging.

▸ **Engineering Services:** Co-development across the entire product lifecycle – from PCB design, hardware and software development to full device industrialisation and market-ready solutions.

▸ **Electronic Manufacturing & System Integration:** SMT and THT assembly, microelectronics, high-mix production and advanced processes such as wire bonding, encapsulation and micro-assembly. Complete box building, including system integration, testing and kitting.

▸ **Precision Plastics:** Tooling and high-precision injection-moulded components, seamlessly integrated into electronic devices, including medical applications.

▸ **Printed Electronics:** Functional printed structures such as sensors, antennas and heating elements, enabled by advanced printing technologies.

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cicor-group

DISCO Hi-Tec Europe

Booth 32

Activities

DISCO is a leading total solution provider for Dicing (Kiru), Grinding (Kezuru) and Polishing (Migaku) technologies. We develop, manufacture and sell precision dicing, grinding and polishing machines as well as dicing blades and grinding/polishing wheels. We are also providing ablation laser and stealth laser cutting, and plasma dicing solutions. Our unique advantage is that we can provide you with not only machines and consumables, but also the total process solutions based on our wide range of application experiences.
Dicing-Grinding Service and Camtek optical inspection service are available at our Munich office. We accept orders even from a small quantity.

Products

DISCO's Precision Machines and Precision Processing Tools:

- Dicing Saws and Dicing Blades
- Laser Saws (Ablation and Stealth Laser)
- KABRA (SiC Ingot Slicing by Laser and Grinding)
- Grinders and Grinding Wheels
- Polishers and Polishing Wheels
- Wafer Mounter
- Die Separator
- Surface Planer
- DBG/Package Singulation

DISCO's Services at Munich office:

- Dicing-Grinding Service
- Camtek Optical Inspection Service (AOI)

Please also visit www.disco.co.jp/eg/products/ and www.dicing-grinding.com/

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Dyconex

Activities

DYCONEX is committed to delivering the highest quality products in the industry – and we back this promise with a deep-rooted expertise in advanced interconnect solutions for medical applications. Our success in the field of high-reliability PCBs is built on multiple strengths: a customer-driven development and design process, decades of experience in low-volume, high-mix manufacturing, and a sharp focus on the most demanding segment of the industry – IPC Class III for medical devices.
What truly distinguishes us is our unwavering dedication to quality, precision, and innovation. We continuously invest in next-generation technologies, particularly in the areas of miniaturization, high-density interconnects, ultra-thin substrates, and advanced via structures. These capabilities are essential for today's and tomorrow's medical devices – from active implants and wearable systems to diagnostics and neurostimulation.
We work in close collaboration with our customers from concept to production, enabling tailor-made solutions that address specific technical, regulatory, and clinical requirements. This integrated approach not only ensures product performance but also supports our partners in accelerating their time to market.

Product

DYCONEX products stand for highest precision, reliability, and technological excellence – specifically designed for demanding applications in the medical field. Our portfolio includes a wide range of highly complex PCB solutions such as HDI and substrate technologies, ultra-thin flex and rigid-flex circuits, special builds with microstructured surfaces, and multilayer designs with features as fine as 10 µm lines/spaces.
Our products are used wherever uncompromising quality is essential – including active implants, audiological devices, neurotechnology systems, portable therapy solutions, ultrasound applications, in-vitro diagnostics, and minimally invasive surgical instruments. They meet the highest standards in biocompatibility, mechanical stability, electrical performance, and long-term reliability – even under extreme conditions.
We process a wide range of high-performance materials including engineered polymers, copper-clad laminates, ceramics, and thin-film metals – all tailored to the specific requirements of the application. Our offering is complemented by services such as laser drilling, microstructuring, selective metallization, and integrated testing and verification solutions to support our customers throughout the product lifecycle.
Thanks to our many years of experience and a fully controlled manufacturing process, we are able to respond flexibly to individual requirements – whether for high-precision prototypes, complex low-volume series, or demanding full-scale production. All products undergo rigorous quality checks and comply with international standards such as ISO 13485, IPC Class III, and customer-specific specifications.

Booth 5

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Egide

Booth 28

Activities

The Egide Group is an international company specialized in the design and manufacturing of hermetic packages for sensitive electronic and optronic components. Our core expertise lies in ceramic packaging, glass-to-metal and ceramic-to-metal sealing, thermal management and special metal alloy processing.
Egide serves critical industry segments like aerospace, defense, security and energy.
The group operates manufacturing facilities in France and the United States.
Egide offers engineering services for custom packaging designs and advanced materials. Our solutions meet stringent requirements for hermeticity, thermal management, reliability, and high-temperature or radiation-hardened applications.
With decades of experience, Egide is a recognized leader in the hermetic packaging market, enabling high-performance and mission-critical systems worldwide.

Product

Hermetic packaging design and manufacturing for sensitive electronic and optronic components.

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egide-group

Electron Mec

Activities

Electron Mec is committed to providing world best in class tools, processes and services to High-Tech players in Europe, meeting and exceeding the requirements of its customers. Based in France, Italy, Germany, Switzerland and Spain we support our partners locally relying on process knowledge and experience.

Product

Electron Mec will be presenting a series of High-Tech products including:

- Controlled Atmosphere and Vacuum solder Reflow Ovens - ATV and DESPATCH
- Plasma Surface Treatment and etching – PVA TEPLA, PANASONIC and SAMCO
- Mask and Maskless Photolithography equipment – SUSS and NANOSYSEM
- Coating and Dispensing systems – MUSASHI, SUSS and HUMMINK
- Machine Vision Systems for Smart Automation and Inspection – MVP, VISIOROBOTICS, TORAY
- Laser Welding Systems for Ermetic Sealing – PYRAMID ENGINEERING
- PVD, CVD, PECVD Deposition technology – NANOVAK, POLYTEKNIK, SAMCO, KANEMATSU
- Hermetic Lids, Boxes and micro-machined parts - SURON
- Wet-Chemical Benches
- Bonding Technology – SUSS and TORAY
- Gloveboxes – KOREA KYION
- Customized PCBs – ELECTRON MEC
- PogoPins and Sockets – INDEPENDENT
- Temperature Control – CORREGE

Booth 2

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Elematec Europe

Booth 33

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Activities

Elematec Corporation is an integrated service company created in 1947, and since then we have continued to grow while wielding flexibility and speed to earn the trust of customers in the fast-evolving electronics industry. As a partner in manufacturing, we align ourselves with customers from the starting line of product development and work together with them to realize one-stop solutions by being involved from the planning and development stage. From there, we support them through the design, prototyping, and mass production stages. Through our industry-leading network in Japan and overseas (totalling over 70 branches) and over 7000 partners world-wide, we deliver products from electronic materials, parts and module products to finished products, on a global scale. We are happy to provide you a solution or missing item(s) in your BOM.

Product

Ceramic Packages: Through our cooperation with NTK Ceramic (Niterra Group), we offer fully customized multi-layer ceramic packages for chip encapsulation in complex applications (MEMS, Hi-Rel, Power, RF, Automotive, Image Sensors, etc.). These ceramic substrates can accommodate larger sizes and finer patterns, while also integrating solutions like Cu-based heat slugs and AlN for improved heat dissipation.
As a set solution for packaging, we provide:

- LIDs and CAPs for sealing, TO-CANs
- Cover glass lids and protective films, for image sensors

In general, for semiconductor manufacturing, processing and handling:

- Chemical products for manufacturing; adhesives, etc., Thermal solutions (TEC, TIM, heat dissipation materials, solutions also for IGBT)
- Tapes; dicing blades, wafer shipping cases and wafer rings, and other products for handling.

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Activities

ELEMCA provides Lab services to understand and improve your electronic technologies, from wafer to component and assemblies :

▸ **Failure & construction analysis**
Computed tomography (3D X-Ray), Lock-in thermography, PHEMOS
FIB, SEM/TEM-EDX

▸ **Reliability**
Environmental testing (thermal cycling / shocks, climatic)
Digital simulation

Portfolio (semiconductor): LYNRED, MURATA, RAKON, TE, TDK/TRONICS, TELEDYNE-E2V

Elemca

Booth 19

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elemca

Finetech

Booth 6

finetech

Activities

Finetech is dedicated in developing equipment for micro-assembly, die bonding, die attach, flip-chip bonding with an accuracy from 0,3µm to a few µm. We target the industries of photonics, microelectronics, mems, medical devices and electronic rework.
Our machines are versatile and allow to realize all assembly processes, from eutectic to ultrasonic bonding, not forgetting epoxy glues and CAF. Of course sample preparation steps as formic acid dispense or plasma activation can also be done in the same easy to use process.
Finetech developped semi-auto tabletop equipment for prototyping and process development to fully automatized machines for volume production.
More information, tech papers and videos on our website: www.finetech.de
Looking forward to meeting you

Product

▸ **Sub-Micron Table Top Die Bonder**
The FINEPLACER® lambda 2 table top die bonding platform can be easily configured for a wide range of applications for process development or prototyping. Numerous process module options and in-field-retrofit capabilities guarantee maximum technological flexibility of the table top die bonder to protect your investment in the face of ever-changing challenges. Due to the table top flip chip bonder's ergonomic machine design and software-supported user guidance, the user remains at the center of action. Powerful optical systems allow the user to keep an overview at all times, even when working in the sub-micron range.

▸ **Automatic Sub-Micron Bonder**
The FINEPLACER® femto 2 is a fully-automated die bonder with 0.3 µ accuracy that offers unrivaled flexibility for prototyping & production environments
The FINEPLACER® femto 2 can be configured and retrofitted at any time to support new applications and technologies. This makes this automatic flip chip bonder a perfect tool and reliable companion as applications migrate from product development to production

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Finetech

GS Swiss PCB

Activities

GS Swiss PCB AG is a specialist for highly miniaturized and reliable PCBs.
In volume production we manufacture substrates in standard technology with lines and spaces of 40 µm, substrate thicknesses down to 12 µm for flex and 30 µm for rigid PCBs and solder mask dam width of 30 µm. Copper filled stacked vias as well as copper filled through holes are standard processes and we offer final surfaces such as ENIG, ENEPIG, electrolytic gold, immersion silver and DIG.
With our sputtering machine for volume production we are able to manufacture PCBs in SAP-technology with lines and spaces down to 10 µm.
Our extensive testing capabilities include IST-testing, 3D topography measurement with submicron precision, analysis be electron microscope as well as ion cross section polishing.

Product

GS Swiss PCB AG excels in the manufacturing of highly miniaturized flex and rigid PCBs with lines and spaces down to 10 µm, cores of 12 µm for flex and 30 µm for rigid PCBs. Testing capabilities include IST-testing and 3D topography measurement. Our PCBs are used in hearing aids, medical implants and sensors as well as on Mars.

Booth 30

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HEF Group

Booth 21

Activities

The HEF Group, a global leader in surface materials engineering, offers its clients a comprehensive service ranging from research activities to process exploitation or component supply, including industrial development and technology transfer.
HEF's expertise in tribology, photonics, and hydrogen technologies is based on five areas of technical and material competence:

- Vacuum deposition and DLC materials
- Ion liquid nitriding
- Laser texturing
- Coated powders
- Friction components

Product

We are industrializing an innovative solution of Polymer Core Solder Balls (PCSB), enabling the creation of reliable and high-performance electronic component assemblies for various applications (aerospace, space, defense, mobility, etc.).
These solder balls offer three significant advantages:

- Increased resistance to thermomechanical stresses compared to standard solutions.
- Controlled standoff between the PCB and the BGA.
- 3D Assembly, Miniaturization
- Alternative to traditional non-collapsible lead solder balls
- Compatible with solder reflow according to IPC-J-STD-001

Polymer core solder balls help improving the lifespan of electrical contact for assembling BGAs on a printed circuit board

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www.hef.fr
HEF Group

Hybrid

Booth 27

Activities

With 30 years of existence, Hybrid SA is your Swiss partner for highly complex projects, from prototyping to serial production, from engineering to industrialization, with excellence driving every step of the process.
We will deploy our expertise in microelectronic assembly techniques like FlipChip, Wirebonding, 01005 size component automatic placement or Diebonding to help you bring your project to life.
We can also assist you with your routing and/or miniaturization layout design, component selection and innovative solution finding.
From medical to industrial, aero to consumer electronics, make sure that your project is in the best hands and contact us today, we will be thrilled to help you.

Product

µ Electronic Manufacturing Services

Application area: IOT (Internet of Things) - Datacom – Avionics – Scientifics – Imagery – Watchmaking – Industry – Medical - Security.

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hybrid-sa

IMAPS

IMAPS – International Microelectronics Assembly and Packaging Society – is a global community of microelectronic related engineers, scientists, manufacturers, end-users and supply chain companies. The Society aims to support the development and growth of the Microelectronics and related industries, and to aid the transfer of knowledge and information. This is achieved through networking, seminars, workshops, short courses, publications, webinars and websites. Members benefit from access to business networking and events at a reduced rate; technical information & receive society newsletters and other publications. IMAPS is the largest Microelectronic Packaging Society in the World!

IMAPS-France (French chapter) is a non-profit organization with 200 members from 110 companies or institutes in France.

IMAPS-France is one out of the 30 IMAPS chapters throughout the World. To that end, we organize events each year, in English language, these are namely: MiNaPAD, POWER, THERMAL.

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www.france.imapseurope.org

Activities

We go beyond design limits to offer you cutting edge semiconductor and electronics assembly, testing and IC package design including LGA, BGA and 2D & 3D customized solutions. Featuring fully supported automated processes, MW microelectronics assemblies, System-in-Package (SiP) & heterogeneous integration. We also offer high level expertise in organic substrate design and manufacturing based on advanced materials, subtractive and mSAP processes.

Miniaturization Technology:

- IC Packaging & System-in-Package (SiP) design, Semiconductor assemblies
- MW microelectronic assemblies, Organic substrates
- Process development & DFM processes

iNPACK Benefits:

- Time To Market (TTM), Design & manufacturing under one roof
- Cost effective solutions, Innovative approach
- Customization options, In-house capabilities: substrates, PCB, micro assembly

Product

▸ Advanced IC Packaging & Organic Substrates – All-in-One Solutions

We offer organic substrate expertise with high-density line/space width and advanced packaging that allows for a smaller form factor, increased functionality, high thermal conductivity, and improved process stability. System-in-Package (SiP) prototypes, or low/mid volume production, Multi-Chip-Modules (MCM), and more; all compatible with aerospace, defense, medical, and other top industry needs.

▸ Advanced Packaging Assembly

Our unique assembly process designs enable you to achieve high-level, customized results with IC packaging solutions tailor-made to your specific applications. Our customers are no longer bound by a specific design process dictated by individual fabricators or semiconductor packaging companies.

▸ Technological Edge

iNPACK are experts in organic substrates and enhanced micro-electronics packaging technologies, with cutting-edge capabilities that deliver complete, comprehensive substrate panel-level manufacturing and engineering support to our customers; in fact, they depend on it. We continuously work to improve interconnections between PCB, Substrate and Semiconductors through advanced technological know-how. Solutions include Organic Substrate materials, IC Substrates, Die Packaging, Multi-Chip-Module (MCM) technology, Chip Packaging and more. Creative solutions and enhanced design flexibility give us the ability to deliver high-speed, thermal and RF pathways that simplify integration processes, that improve overall system reliability.

iNPACK

Booth 10

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H'aoman 10
Migdal H'aemek
Israel

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Insidix

Booth 36

Activities

Insidix is a company specialized in imaging and inspection technologies. As both a manufacturer of thermomechanical deformation measurement (TDM) equipment for the electronics and semiconductor industries and a service provider through its laboratory in Grenoble, INSIDIX has 30 years of experience in electronic component inspection.
Its TDM technology, unique and patented by INSIDIX, is sold worldwide to major semiconductor and electronics companies.
The laboratory offers a wide range of services, including design inspection, process control, PCB reverse engineering, and technology validation.
Key inspection and analysis services include: X-ray radiography, X-ray tomography, metallographic cross-sectioning, SEM/EDX inspection, acoustic microscopy, infrared thermography, TDM, and more.
INSIDIX remains a human-scale company, known for its responsiveness and strong customer focus.

Product

- TDM Technology : thermo mechanical analysis (warpage and CTE)
- Lab analysis : XRAY 2D/3D, C-SAM, LIT, Cross sections, MEB/EDX, MMT, Laser and more
- Distribution of XRAY systems (NIKON), SAM systems (PVA Tepla OKOS) and SEM (Zeiss).

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Intraspec Technologies

Activities

Founded in 1994, iST began its business from IC circuit debugging and modification and gradually expanded its scope of operations, including Failure Analysis, Reliability Assurance, Material Analysis and so on. iST has offered full-scope verification and analysis services to the IC engineering industry, its customers caver the whole spectrum of the electronics industry from IC design to end product s. iST aims to expand its market presence in Europe. Beyond addressing customers' pain points, the company strives to offer innovative solutions to help clients work more efficiently and effectively.

Product

Each investigation is tailored to the customer's technology, failure mode, and technical constraints. The objective is to deliver clear technical conclusions and practical recommendations. Examples of techniques that may be used include, without limitation:

- Optical and digital microscopy
- X-ray inspection
- Scanning electron microscopy
- Elemental and material analysis
- Cross-section preparation and inspection
- Electrical characterization
- Magnetic microscopy
- Lock-in thermography
- 3D die thinning
- High-voltage testing
- Leak testing and hermeticity assessment
- Thermal, mechanical, or environmental stress testing
- Reliability testing and failure reproduction
- Root cause analysis and technical reporting

Booth 31

INTRASPEC
TECHNOLOGIES
The root to Reliability

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intraspec-technologies

Kyocera

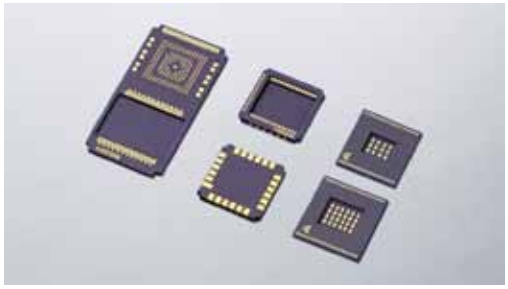
Booth 7

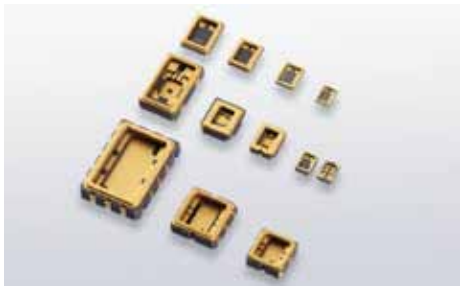
THE NEW VALUE FRONTIER

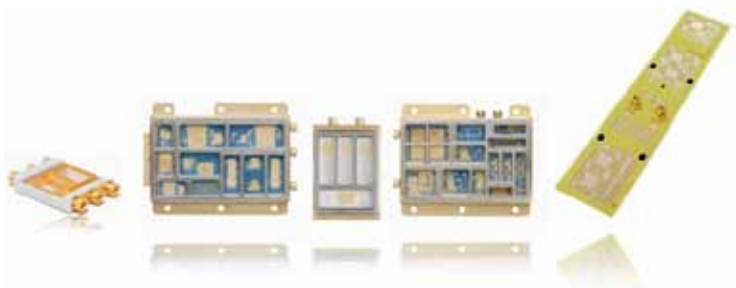
KYOCERA

Activities

High-reliability ceramic packages and substrates help to miniaturize components used in smartphones, fiber optics, automotive electronics (such as headlight LEDs), and a wide range of other applications. Materials, processing, and design technologies to ensure unparalleled substrate and package performance.
The rapid advancement of information and communications technologies (ICT) and the internet have fueled an extraordinary increase in the functionality and performance of electronic devices. Our organic packages help to support these developments.
Our other business domains extend to a wide range of industrial fields, such as digital equipment, automotive manufacturing, and energy, based on our organic material technology.







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Metronelec

Activities

Since 1975, Metronelec has specialized in the manufacture and sale of equipment for the electronics and microelectronics industries. Originally specialized in quality control, Metronelec has developed in the production area for several years and today offers a wide range that covers all processes from design to production.
In addition to the French parent company, Metronelec has branches in China, Tunisia and Morocco.
Metronelec equipment is marketed all over the world thanks to a large network of distributors trained to perform maintenance and local technical support.

Product

Manufacturer of solderability tester for components and ionic contamination analyzer
Distributor of equipment for the assembly of printed circuits online/offline and consumables for the electronics, optoelectronics and semiconductor industry in France
Main representations :

- NORDSON DAGE: multifunction bond tester system. X-RAY Systems
- SIKAMA: reflow ovens.
- FINETECH: Flip-chip bonders
- KOH YOUNG: 3D Paste Inspection systems and 3D AOI
- ITW EAE: screen printing systems

Booth 12

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metronelec

Micronor

Booth 4

Activities

More than 50 years as subcontractor expert in custom hermetic sealing & hermetic interconnections for harsh environment (pressure, intensity, tension, temperature, etc...)
Design and production of prototypes, small and medium series, based on customer technical specifications.
Small size of pieces (Ø 0,2 mm up to 150 mm)

- Glass to Metal seal (including dilver P1 (kovar) and titanium) and high and low temperature brazing (ceramic, sapphire, etc...)
- Base and precious metals electroplating (specific 99,99% pure gold for space applications)
- Hermeticity : Leak rate less than 10-8 mbar.l/s
- Electric isolation : Isolation resistance over 10 GΩ
- Breakdown voltage : from 500 to 3000 V
- Pressure : up to 3000 bars
- Operating temperature : from -180°C to +300°C (according to coating)

Precious metal electroplating processes (gold, silver) and common metal (tin, copper) for industrial applications (space, defense, etc...) – specific 99.99% pure gold electroplating process for space application

Product

Non exhaustive products list (based on customer's technical specifications) : feedthroughs, electronic packages, sensors, relay bases, connectors, isolators, igniters bases, medical implants, etc.

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Micro System Technologies

Activities

The Micro Systems Technologies (MST) Group provides innovative components and services for technologically advanced industries that demand miniaturization, exceptional performance, and the highest level of reliability. Examples are medical technology, aerospace & aviation, and challenging applications in telecommunications, industrial electronics, and sensor technology.

Active around the globe, the MST group consists of five technology companies with more than 1,100 employees in three countries, all of which offer their customers integrated solutions from conceptual design to series production.

The MST Group's quality system is derived from the stringent requirements of life-sustaining implants and ensures 100 % traceability of processes and materials. The companies are ISO 13485 and/or ISO 9001 and/or ISO 9100 certified.

For more information, please visit our virtual showroom: www.showroom.mst.com

Booth 3

MST
Micro Systems Technologies
engineering for life

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ONTOS Equipment Systems

Booth 15

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Activities

ONTOS Equipment Systems is a leading supplier of atmospheric plasma machines designed to replace vacuum equipment and wet processing to produce contamination-free, highly-activated surfaces to enhance cost, yield, and throughput in microelectronics manufacturing.
Our customers include RF, Optoelectronic and Defense market leaders. Headquartered and made in the USA with established world-wide distribution channels, sales and service is provided in more than 20 countries around the world.
Aside from other solution providers is our ability to work collaboratively with our customers to specifically tailor a system solution around their specific application and process requirements. This is achieved by continuously introducing, implementing, and integrating the latest, most advanced technology with proven robustness and reliability.

Product

▸ ONTOS Clean

The ONTOS Clean is a Standalone Semiautomated System for Surface Preparation using a patented Atmospheric Plasma with a unique design enabling without any modification using oxidizing or reducing chemistry. Ontos performs Cleaning, Eliminates the Organic Contamination, Activates Surfaces and Remove Oxidation.
An Innovative Process applies a gaseous passivation that delays the re-oxidation of the metallic surfaces.
Standard Plasma Head 25mm, 40mm, and 105mm.
Versatile Chemistry: ONTOS Clean uses Helium or Argon as the carrier gas because of their metastable energies. Customers can choose to introduce Oxygen (cleaning and activation), Hydrogen (oxide removal) or Nitrogen

▸ ONTOS IS

OEM version of the ONTOS Plasma Head for integration into third party equipment. The Plasma Curtain is available in several widths (down to 10mm) to enable optimization of the gas consumption on smaller devices or to adapt to larger devices. Integration engineering resources available.

Plasmatreat

Activities

Atmospheric Plasmatreat treatment machines are a key asset for achieving cost-effectiveness and process reliability.

- For transparent, scratch-proof coating of displays, it significantly reduces the reject rate and ensures a flawless appearance.
- When printing electrically conductive coatings on printed circuit boards, prior plasma activation, microfine cleaning ensure that the coating will adhere securely.
- In chip packaging, Openair-Plasma® microfine cleaning eliminates the need for a vacuum chamber, so process flows can be greatly simplified.
- The Openair-Plasma® process is completely potential free, it facilitates the complex process of conformal coating by extending the process window and increasing the quality of the coating.
- On cell phones and laptops, plasma pretreatment is used for VOC-free finishes ; it avoids the use of VOC's (volatile organic compounds)

Product

Plasmatreat's Openair-Plasma® cleaning and activation, along with the innovative REDOX-Tool, provide advanced solutions for oxide-free surfaces, in order to enhance adhesion, electrical performance, and overall reliability. It is possible to remove oxide layers in an inline process. This requires only a combination of nitrogen and hydrogen. This process does not need environmentally harmful formic or citric acid. Designed as a tunnel solution, the system has 3 zones: pre-heating, reduction by plasma, cooling zone. Production flexibility is provided. If required, the tool can be equipped with 2 tunnels to increase throughput. Optionally, all process-relevant data can be recorded and made available via SECS/GEM. Optional, a barcode scanner ensures the traceability.
This results in improved joint quality, better electrical and thermal conductivity, and enhanced overall reliability of the semiconductor devices. Additionally, the use of fluxless processes can simplify the manufacturing process and eliminate problem of flux residues. Using the REDOX® -Tool in TCB processes, ensures that oxide layers do not negatively affect the performance and reliability of the power module throughout the assembly process, from the DCB substrate to die attach, wire bonding, sintering and moulding.

Booth 26

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Protavic International

Booth 23

Activities

Protavic International is a French company, that designs and develops resins, adhesives and inks for the electronic industry, with operations in Europe, the United-States, South Korea and China.
Protavic International is a subsidiary of Protex International, which develops, manufactures and markets specialty chemical additives.
Protavic International offers high-value added solutions for optimized industrial processes. From the component to the final electronic card,
Protavic products glue, protect and bond in all steps of the process. It is possible to use the products as Die-Attach, Dam & Fill, Underfill, encapsulant, thermal dissipator...
Protavic International is present in many sectors such as electronics, aerospace, acoustic, automotive, medical, optoelectronic, solar energy...
Domains : Conductive and insulating adhesives, Die attach, Terminations, Dam&Fill, Glob top, Thermal dissipation, Encapsulation and Potting, Underfill, Conductive inks, Silver nanowires. Epoxy, Acrylic, PU, Polyimide, Silicone and Hybrid products.

Product

Resins and Adhesives for the electronic industry

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Roartis

Activities

Roartis stands for innovative and quality electronic adhesives, resins, coatings, inks and sinter-materials, for demanding, high reliability applications developed and produced in Europe!
Roartis' materials have been used for many years in high reliability applications and markets such as the semiconductor industry, aviation, medical, aerospace, defense, energy, automotive and industrial electronics.
With state of art laboratories and manufacturing facilities in the center of Europe, optimized and focused towards small to medium sized volume applications, Roartis is well positioned to meet the stringent requirements of the current and future electronic market requirements.
All the materials developed and commercialized by Roartis are compliant to the latest environmental regulations, such as RoHS, REACH, WEE and the End-Of-Life-Vehicles directive.

Product

Our product portfolio includes:

- Electrically conductive adhesives & sinter materials
- Insulating adhesives
- Thermally conductive adhesives
- High temperature resistant materials
- Underfills
- Glob top and Dam & Fill resins
- Liquid resins for encapsulation and potting,
- Flame retardant materials, UL94-V0 certified,
- Optically clear adhesives, coatings and encapsulants
- UV-curable adhesives & inks, for photonics packaging
- Refractive index matching materials

Booth 14

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SERMA
Microelectronics

Booth 9

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serma-microelectronics

Activities

SERMA Microelectronics brings over 30 years of expertise to the table, specializing in the provision of chips and the assembly of semiconductors for industries where reliability is paramount, such as defense, aerospace, and medical sectors.
With a workforce of 90 employees as of 2023, spread across two production facilities located in Périgny (La Rochelle) and Pinsaguel (Toulouse), and boasting a clean room spanning over 1000 m², SERMA Microelectronics not only supplies and manufactures specific substrates but also assembles trustworthy products using a variety of technological components.
SERMA Microelectronics is equally involved in MCO (Maintenance in Operational Conditions) issues by maintaining proven processes and making sure they are long-lasting, as well as in the development of technological bricks that can be used to integrate more recent types of technology (MEMS, High pin count devices, MMIC, BGA, etc.), thus combining its microelectronics and SMD transfer resources in manufacturing SiPs (System In Package).
With a robust background in assembling Hi-Rel components, particularly hermetic ceramic and organic substrates, SERMA Microelectronics collaborates closely with its clients to navigate the intricacies of specific technologies and mission profiles, developing tailored integration processes to meet their exacting requirements.

Product

SERMA Microelectronics offer is subdivided in three main activities:

- The Engineering department, in charge of the development of various assembly processes in order to industrialize the customers' products. This division is also responsible of the design of organic and ceramic substrates according to the scope and the complexity.
- The Production department, which implements assembly processes. This pole also includes:
- The Die Management division which deals with active devices (procurement, sawing, visual inspection, and storage)
- The Thick Layers pole, which defines and implements inks screen- printing to produce substrates with high environmental performance.
- The Thin Film Department, which defines and produces substrates for microwave applications and high reliability photonics, using sputtering and photolithography technologies.
- The Test division, in charge of the functional verification of manufactured products through reliability and qualification sequences.

SET

Activities

Based in France, SET is a world leading supplier of high accuracy Flip-Chip Bonders excelling in high-end, demanding applications.
Since 1975, we have accompanied laboratories and industries, which look for a high precision and an important reliability in the assembly of their components. We accelerate their developments of the chips of future thanks to our robust and precise Flip-Chip Bonders.
With Flip-Chip Bonders installed worldwide, we are globally renowned for the high post-bond sub-micron accuracy and the high flexibility of our equipment. Ranging from manual loading version to fully automated version, our systems cover a wide range of applications and offer the unique ability to handle both fragile and small components onto substrates and wafers up to 300 mm.

Product description

- ACCµRA M, ± 3 µm post-bond accuracy,
- Manual Flip-Chip Bonder for universities and R&D institutes
- ACCµRA100 / OPTO, ± 0.5 µm post-bond accuracy
- Semi-automatic Flip-Chip Bonder for optoelectronics and silicon photonics
- ACCµRA Plus, ± 0.5 µm @ 3 σ post-bond accuracy
- Automatic Flip-Chip Bonder designed for production
- FC150, ± 1 µm post-bond accuracy / FC300, ± 0.3 µm post-bond accuracy
- Flip-Chip Bonders for advanced R&D and pilot line oriented
- NEO HB, ± 0.5 µm @ 3 σ post-bond accuracy
- Automatic Flip-Chip Bonder for hybrid bonding, dedicated to production

Booth 8

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SET Corporation

Synergie CAD PSC

Booth 17

Activities

SYNERGIE CAD PSC is specialized in Semiconductor IC's industrialisation and production services.
Our internal industrial capabilities located in France (Toulouse) allow to provide full back-end services from our internal supply chain in Europe/France for multiple applications (Consumer/Industrial, AI, Automotive, Space & Defence, ...), including:

- Packaging – Assembly : with our internal Packaging for small and mid series production
- Test Development and Test Production (from digital to RF-MMW)
- Reliability Qualification Laboratory
- Hardware development and fabrication (Test loadboards, Probe cards, electronic boards, ...)
- Logistics and Supply chain

For large series, our privileged partnership with Tier1 OSAT allow us to provide full TurnKey services to our customers from GDS or wafers to delivery of Finished Goods

Product

Semiconductors Back-End Engineering and Industrial services

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Synergie Cad PSC

Taipro Engineering

Activities

Taipro offers electronic design and packaging services in microelectronics from prototyping to production. By combining its electronic know-how and microelectronics assembly capabilities, Taipro develops miniaturized electronic systems that are free of any constraints.

Technologies:

- Die placement
- Flip-chip
- Wire bonding
- Encapsulation

Booth 24

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UniTemp

Booth 22

UNITEMP
Universal Temperature Processes

Activities

Thanks to our in-house development and production, our team at UniTemp is able to react quickly and with high quality to changes and changing conditions.
The continuous improvement of our devices ensures that we are as close as possible to our customers' requirements.
This is why each of our appliances also offers a wide range of different options and upgrades.
For 24 years, UniTemp has been active in the field of reflow solder furnaces as well as RTP annealing systems. We specialize in equipment for thermal processes.
We mainly supply customers in the R&D sector for the evaluation of semiconductor and other processes. Our target group are institutes, universities and the development departments of semiconductor manufacturers.
We are located in Bavaria close to Munich.

Product

Reflow solder ovens: We provide reflow solder systems which enable flux-less, lead and void free soldering, encapsulation of housings, soldering of power devices and solder bump reflowing.
Semiautomatic wire bonders: Our wire bonders have 3 motorized axes with an accuracy of 1,0 µm. They come with a fine table motion and provide as well deep access bonding. They can be served with gold and aluminum wires.
High precision hot plates: Our high precision hot plates are temperature controlled via a digital target and actual value display including a overheating protection. The substrates are fixed by vacuum.

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Call for Abstracts: POWER 2026

From Nano to Macro Power Electronics and Packaging European Workshop
Tours, France **November 26th 2026**

Building on the remarkable success of the Power Electronics Workshop which has been organized for the past 16 years, IMAPS-France is proud to announce the 16th edition of the Power Electronics and Packaging Technical Workshop.
Organized in partnership with GREMAN (UMR 7347) Polytech-Tours, and sponsored by ST-Microelectronics, CERTeM and Polytech Tours, this highly anticipated event will take in **Tours, France, on Thursday, November 26th, 2026**. Tours is an ideal location, situated in the scenic Loire Valley, famous for its magnificent riverside castles. Please note that the entire event will be held in English. **Save the date!**

We invite speakers to submit abstracts relating to the following topics:

- Power management for transportation and industrial systems
- Energy harvesting systems, from nano to macro (smart grid, wind energy, photovoltaic, etc.)
- Energy conversion systems– from power to emission (lighting, ultrasonic, infrared, etc.)

These topics could be developed around several themes, such as:

- New materials and substrates dedicated to power electronics
- Thermal or thermo mechanical or regulatory constraints (RoHS regulation, REACH, etc.)
- Dedicated technologies for integration and optimisation of power systems, including passive components (weight and size reduction, yield improvement, efficiency, etc.)
- Innovative technologies, materials and processes dedicated to interconnection and packaging (die attach, bonding wire & ribbon wires, 3D power components, etc.)
- Reliability and failure modes (impacts linked to technologies, thermal constraints, radiation, etc.) predictive methods, design of experiments, reliability
- High current and high voltage or extremely high voltage: impact on packaging technologies

Presentations duration will be 25 minutes, including 5 minutes for questions and answers. The abstract submission deadline is August the 31st. Please submit abstracts in English (Conference official language) and word format, including the names of the company or institution, the speaker and associated author(s), the title of the conference and an abstract of 250-600 words. Paper acceptance will be communicated prior to September the 20th
Following the first workshop day, IMAPS will organize in the evening a specific event followed by a dinner.

▸ **Technical Commitee**
Daniel Alquier, GREMAN Laboratory, France, Co-chairman

Laurent Barreau, STMicroelectronics Tours, France, Chairman

Lars Boettcher, FRAUNHOFER Institute, Germany

Cyril Buttay, AMPERE Laboratory, France

Jean-Luc Diot, PRIVATE, France

Franck Dosseul, MODULEUS, France, Co-chairman

Guo-Quan Lu, Virginia Tech, USA

Stéphane Bellenger, STMicroelectronics Grenoble, France, Chairman

For further information, please contac:
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www.france.imapseurope.org

Call for Abstracts: THERMAL 2027

20th Advanced Technology Workshop on Micropackaging and Thermal Management
La Rochelle, France **March 17th – 18th 2027**

We are pleased to open the call for papers of the 20th Advanced Technology Workshop on Micropackaging and Thermal Management that will be held in **La Rochelle** on **March 17th and 18th, 2027**. This yearly conference has grown year after year by the number of presented papers and attendees.

Be part of a successful 2027 edition and be sure to submit your abstract on time. The workshop sessions will include the following topics. Papers are invited in following areas:

- Cooling solutions for microelectronics packaging,
- Heat conductive materials at chip, board, sub-system and system levels,
- Advances in PCBs for thermal management, PCB embedded components included,
- Heatsinks, heat pipes and change phase materials,
- Liquid and phase change cooling,
- Thermal modeling and simulation, Machine Learning and AI optimization,
- Innovative cooling solutions,
- Thermal management of optoelectronics components (LEDs, IR sensors...),
- Overviews or examples of products, systems cooling, power electronics, automotive transport,
- Temperature-related or thermal cycles-related reliability of electronic components.

Speakers will submit 200-300 words abstract detailing their presentation (20 minutes + 5 minutes for questions), no later than **10th, January 2027**.

Speakers pay a reduced registration fee (including MERCURE hotel accommodation for 2 nights and meals) and are also requested to attend the entire workshop to maximize opportunities of exchanging with other attendees and exhibitors.

Notification of acceptance by the Technical Committee: 20th, January 2027. After notification of acceptance, you commit to attend the workshop or delegate someone else.

Please respond to imaps.france@orange.fr

▸ **Conference Chairmen**
Jean-Yves Soulier (Safran Data Systems)
Bruno Levrier (Bruno Levrier Expertises)
Jean-Pierre Fradin (ICAM Toulouse)

▸ **Technical Program Committee**
Mohamad Abo Ras (Berliner Nanotest)
Boguslaw Wiecek (Technical University Of Lodz)
Dave Saums (DS & A Llc)
Thomas Harder (ECPE)
Raphaël Sommet (Xlim Université de Limoges)
Sandrine Feneyrou (Safran Data Systems)
Vincent Ayel (CNRS-ISAE ENSMA-Université de Poitiers)

EMPC 2027

The 26th European Microelectronics and Packaging Conference (EMPC) & Exhibition
Ingolstadt, Germany **September 14-16, 2027**

The European Microelectronics and Packaging Conference (EMPC 2027) is the premier international conference for microelectronics packaging, owned and sponsored by IMAPS-Europe and co-sponsored by IEEE-EPS. The event brings together researchers, innovators, technologists, and business and marketing managers with a shared interest in semiconductor packaging. The program will focus on both current industrial needs and trends, as well as on long-term academic solutions such as:

- Advanced Packaging & System-Integration
- Materials and Processes
- Design, Modelling and Reliability
- Markets and Developments

In addition to the technical sessions, EMPC will feature a comprehensive exhibition, offering companies and institutions the opportunity to present their latest products, technologies, and services. This exhibition provides an ideal platform for networking, business development, and discovering cutting-edge solutions in microelectronics packaging.

Co-Sponsored by:

IEEE

IEEE ELECTRONICS PACKAGING SOCIETY

Organized by:

iMAPS EUROPE

Roland Schäfer @ Pixabay

IMAPS France Chapter
International Microelectronics Assembly Packaging Society

IMAPS France is a non-profit organization with 96 members in 2026 from 50 companies or institutes in France and neighboring countries (Belgium, Switzerland).
IMAPS France is one of out the 30 IMAPS chapters worldwide.
Our mission is to promote and to disseminate knowledge and know-how related to the packaging and assembly of semiconductor devices.

The Board

Alexandre Val	IMAPS France President
Jean-Yves Soulier	Treasurer
Bruno Levrier	Secretary
Jean-Charles Souriau	Technical Manager

Membership Registration Form 2026

☐ 100 € Individual member
☐ 50 € Retired member
☐ 20 € Unemployed member, students
☐ 350 €*HT Corporate SMC
☐ 650 €*HT Corporate

Name: .....

First Name: .....

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▸ **Condition of payment:**
- by chèque to IMAPS
- Payment by bank transfer
- Registration and Payment online https://event.imapsfrance.org
- Purchase order (PO)

IMAPS bank references
LCL Versailles Saint Louis
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Code BIC : CRLYFRPP

Next IMAPS Events Calendar

2026

▸ September 9th – 11th **10th ESTC 2026**

The 10th IEEE Electronics System-Integration Technology Conference (IEEE ESTC 2026) is the premier international event in the field of electronics packaging and system integration. The conference is organized every two years in Europe and is supported by IEEE-EPS in association with IMAPS Europe. The 11th IEEE ESTC will be taking place in Helsinki, Finlande.
www.estc-conference.net

▸ November 26th **16th POWER 2026**

From Nano to Macro Power Electronics and Packaging European Workshop
Tours, France
Following the success of the Power Electronics Workshop organized over the past 15 years in partnership with GREMAN (UMR 7347) and Polytech-Tours, sponsored by ST-Microelectronics, CERTeM and Polytech Tours, IMAPS-France proudly announces the 16th edition of the Power Electronics and Packaging Technical Workshop to be held in Tours, France on Thursday, November 26th, 2026. The city of Tours is located along the scenic Loire Valley which is famous for its castles built along the river. The event will be held in English.

2027

▸ March 17th – 18th **Thermal 2027**

20th ATW on Micropackaging and Thermal Management
La Rochelle, France
We are pleased to announce of the 20th Advanced Technology Workshop on Micropackaging and Thermal Management that will be held in La Rochelle on March 17th and 18th, 2027. This yearly conference has grown year after year by the number of presented papers and attendees.

▸ June 9th – 10th **MiNaPAD 2027**

Micro Nano Electronics Packaging and Assembly, Design and Manufacturing Forum
Grenoble France

▸ September 14th – 16th **EMPC 2027**

The European Microelectronics Packaging Conference
Grenoble France
The European Microelectronics and Packaging Conference (EMPC 2027) is the premier international conference for microelectronics packaging, owned and sponsored by IMAPS-Europe and co-sponsored by IEEE-EPS. The conference program will focus on industrial needs and trends and on academic long-term solutions. The event brings together researchers, innovators, technologists, business and marketing managers with an interest in semiconductor packaging.

Organizer

▸ **IMAPS France**
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IMAPS – International Microelectronics Assembly and Packaging Society – is a global community of microelectronic related engineers, scientists, manufacturers, end-users and supply chain companies. The Society aims to support the development and growth of the Microelectronics and related industries, and to aid the transfer of knowledge and information. This is achieved through networking, seminars, workshops, short courses, publications, webinars and websites.
Members benefit from access to business networking and events at a reduced rate; technical information & receive society newsletters and other publications.
IMAPS is the largest Microelectronic Packaging Society in the World!
IMAPS-France (French chapter) is a non-profit organization with 200 members from 110 companies or institutes in France and neighbouring countries (Belgium, Switzerland, Morocco, Spain, Portugal).
IMAPS-France is one out of the 30 IMAPS chapters throughout the World.
To that end, we organize events each year, in English language, these are namely: MiNaPAD, POWER, THERMAL and next year EMPC 2025 a European Event.

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13TH MICRO/NANO-ELECTRONICS PACKAGING AND ASSEMBLY, DESIGN AND MANUFACTURING FORUM

MiNaPAD Forum 2027

June 9th – 10th

Minatec

Grenoble – France

- Exhibitions
- Conferences

Organized by IMAPS France – International Microelectronics Assembly and Packaging Society
17 rue de l'Amiral Hamelin – 75016 Paris – France
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March 17th – 18th 2027
La Rochelle
France

Mercure Océanide
Vieux Port Sud

20th European Advanced Technology Workshop on Micropackaging and Thermal Management

Organized by IMAPS France – International Microelectronics Assembly and Packaging Society
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